

#2 PA Amndt. A  
10-3-01  
R. J. Lee

PATENT  
Attorney Docket No. SAM-0201

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Jong-hyon Ahn  
Filing Date: Herewith  
Title: METAL INTERCONNECT LAYER OF SEMICONDUCTOR DEVICE  
AND METHOD FOR FORMING A METAL INTERCONNECT LAYER

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.10

"Express Mail" Mailing Label Number EL799313947US I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated below and is addressed to BOX PATENT APPLICATION, Assistant Commissioner for Patents, Washington, DC 20231.

June 12, 2001  
Date

Vanessa Marakas  
Vanessa Marakas

BOX PATENT APPLICATION  
Assistant Commissioner for Patents  
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to prosecution on the merits, please amend the above-identified application as follows:

In the Claims

Please amend the claims as follows:

#1

10. (Amended) A metal interconnect layer for a semiconductor device, comprising:

- a first upper portion having a first width;
- a second middle portion having a second width, the second width being wider than the first width; and
- a third lower portion having a third width, the third width being narrower than the second width.